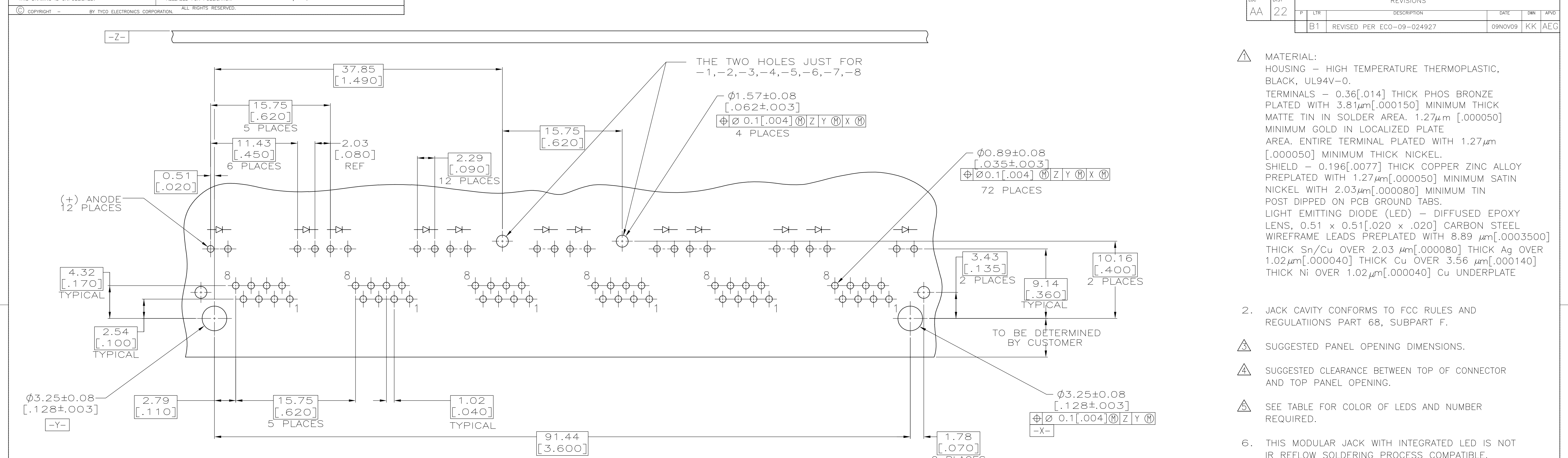




SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)

- MATERIAL:**
HOUSING – HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
TERMINALS – 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81 μ m[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27 μ m [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 μ m [.000050] MINIMUM THICK NICKEL.
SHIELD – 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27 μ m[.000050] MINIMUM SATIN NICKEL WITH 2.03 μ m[.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
LIGHT EMITTING DIODE (LED) – DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 μ m[.0003500] THICK Sn/Cu OVER 2.03 μ m[.000080] THICK Ag OVER 1.02 μ m[.000040] THICK Cu OVER 3.56 μ m[.000140] THICK Ni OVER 1.02 μ m[.000040] Cu UNDERPLATE
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- SUGGESTED PANEL OPENING DIMENSIONS.**
- SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.**
- SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.**
6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
- FOR 5406554-9, NO REAR GROND TAB.**
- OBsolete PARTS: OBsolete CIS STREAMLINING PER D.RENAUD/D.SINISI**

